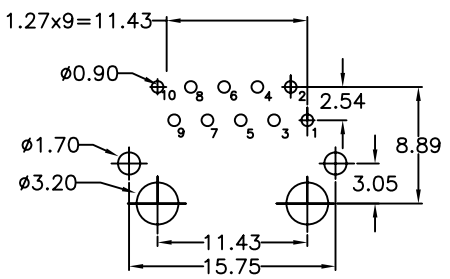
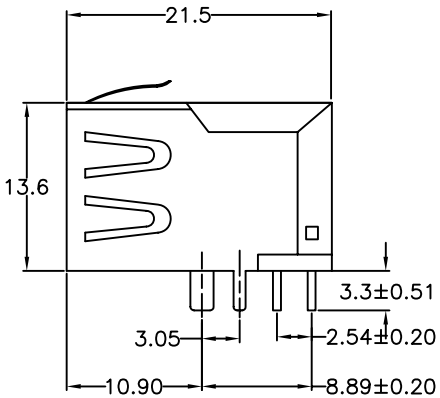
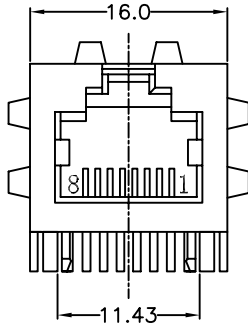
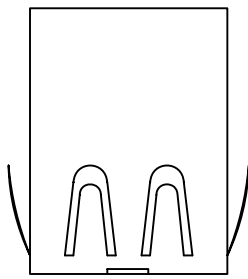


REV.	SPECIFICATION	ECN NO.	APPD.



P.C. Board Layout

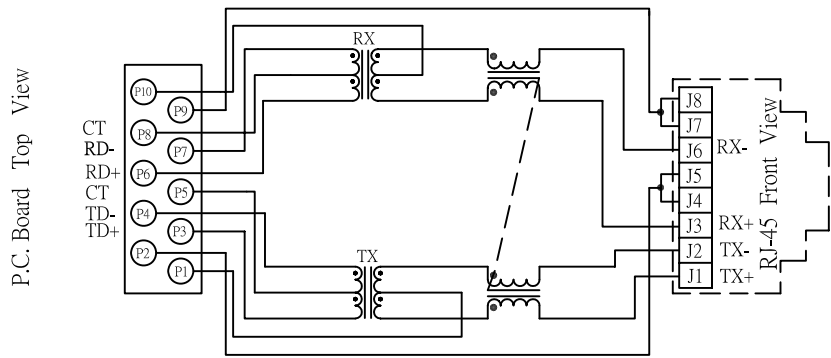
Mechanicals

Housing: High Temperature Plastic UL94V-0.
Insert: Copper Alloy, Thermoplastic Polyester Glass Filled UL94V-0.
Plate: Thermoplastic Polyester Glass Filled UL94V-0.
Contact Pin: Copper Alloy.
Shielding: Copper Alloy.

Electrical Specifications@25° C:

Turn Ratio(±5%): 1CT:1CT.
 OCL(100KHz/0.1V@8mA): 350uH Min.
 Insertion Loss(dB Max): -1.2dB(1-100MHz)
Return Loss(dB Min):
 -16dB(1-30MHz), -14dB(40MHz), -13dB(50MHz), -12dB(60-80MHz)
Cross Talk(dB Min):
 -45dB(30MHz), -40dB(60MHz), -35dB(100MHz)
DCMR(dB Min):
 -43dB(30MHz), -37dB(60MHz), -33dB(100MHz)
 HI-Pot Test : 1500Vrms/0.5mA/2Sec.
 Operating Temperature: 0° C~+70° C.

***RoHS Compliant**



8949-M 8 8 1 /06 S C 1 B A /A002
 Series Position 8: 8 Contacts loaded 1: 1 Port 06: 6 μ" Gold Plated S: Shield 1: With B: Black A: Tray /A002
 15: 15 μ" Gold Plated Grounding Package
 30: 30 μ" Gold Plated
 50: 50 μ" Gold Plated

Tolerances	Drawn No.	8949D02107		Title:		OUPIN OUPIN ELECTRONIC(KUNSHAN) CO., LTD.	
x = ±0.5	Projection	⊕ ⊞		8949-M Series Rj-45 Modular Jack			
.x = ±0.35	Unit	mm	Scale			1:1	
.xx = ±0.25	Drawn By	Peggy 06/10'11		①560		Ver.No.	A4